

Transient Voltage Suppressors for ESD Protection

General Description

The LESD8D5.0CET5G is designed to protect voltage sensitive components from ESD and transient voltage events. Excellent clamping capability, low leakage, and fast response time, make these parts ideal for ESD protection on designs where board space is at a premium. Because of its small size, it is suited for use in cellular phones, MP3 players, digital cameras and many other portable applications where board space is at a premium.

Applications

- Cellular phones
- Portable devices
- Digital cameras
- Power supplies

Features

- Small Body Outline Dimensions
- Low Body Height
- Peak Power up to 180 Watts @ 8 x 20 μ s Pulse
- Low Leakage current
- Response Time is Typically < 1 ns
- ESD Rating of Class 3 per Human Body Model

LESD8D5.0CET5G



SOD882



Ordering information

Device	Marking	Shipping
LESD8D5.0CET5G	D5	10000/Tape&Reel

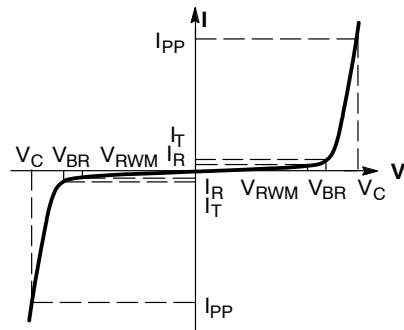
Absolute Ratings ($T_{amb}=25^{\circ}C$)

Symbol	Parameter	Value	Units
P_{PP}	Peak Pulse Power ($t_p = 8/20 \mu s$)	180	W
T_L	Maximum lead temperature for soldering during 10s	260	°C
T_{stg}	Storage Temperature Range	-65 to +150	°C
T_{op}	Operating Temperature Range	-40 to +125	°C
T_j	Maximum junction temperature	125	°C
	IEC61000-4-2 (ESD)	air discharge contact discharge	± 30 ± 30 KV

Electrical Parameter

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
P_{pk}	Peak Power Dissipation
C	Capacitance @ $V_R = 0$ and $f = 1.0$ MHz



Electrical Characteristics

Device	V_{RWM} (V)	I_R (μA) @ V_{RWM}	V_{BR} (V) @ I_T (Note 1)		I_T	V_C (V) @ $I_{PP} = 1$ A	V_C (V) @ $I_{PP} = 12$ A	I_{PP} (A)	P_{PK} (W)	V_{Clamp} @ $I_{TLP} = 16$ A(V)	C (pF)
	Max	Max	Min	Max		Max	Max				
LESD8D5.0CET5G	5.0	0.1	5.5	7.5	1.0	8	11	16	180	9.8	45

*Surge current waveform per Figure 1.

1. V_{BR} is measured with a pulse test current I_T at an ambient temperature of 25°C .

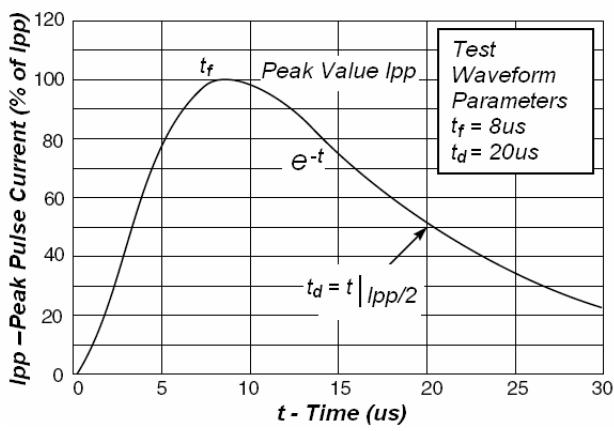


Fig1. Pulse Waveform

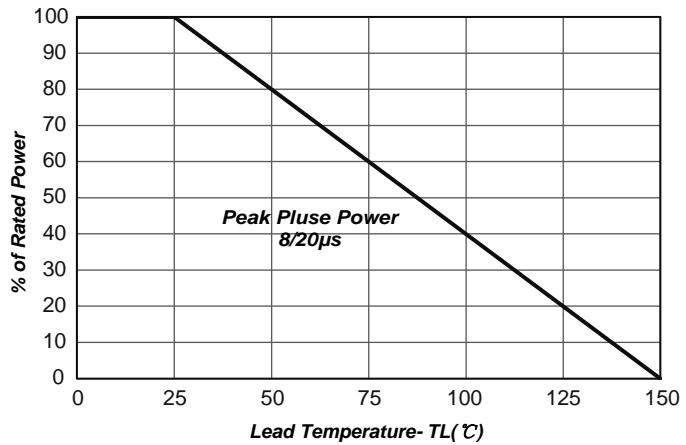


Fig2. Power Derating Curve

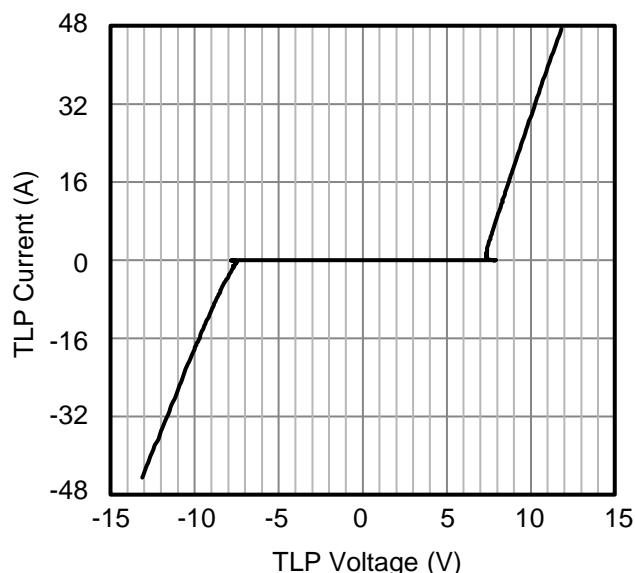


Fig3. TLP Measurement

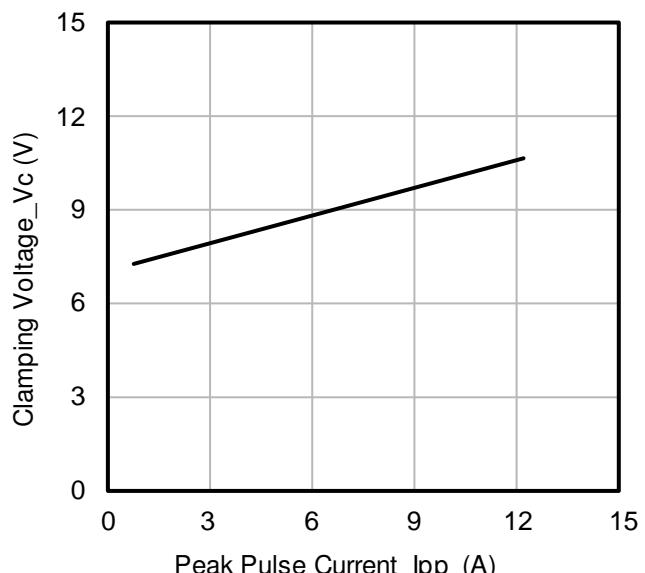
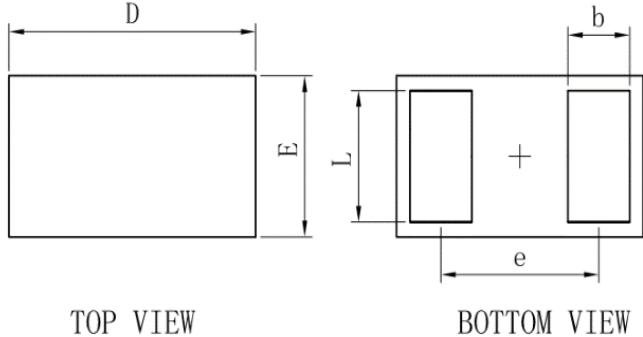
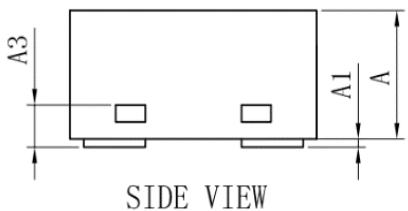


Fig4. Clamping Voltage vs. Peak Pulse Current

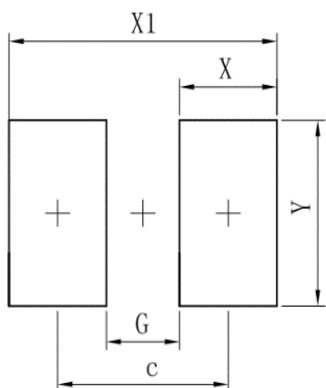
OUTLINE AND DIMENSIONS



SOD882			
Dim	Min	Typ.	Max
D	0.95	1.00	1.05
E	0.55	0.60	0.65
e	-	0.64	-
L	0.44	0.49	0.54
b	0.20	0.25	0.30
A	0.43	0.48	0.53
A1	0	-	0.05
A3	0.127REF.		
All Dimensions in mm			



SOLDERING FOOTPRINT



Dimensions	(mm)
c	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70